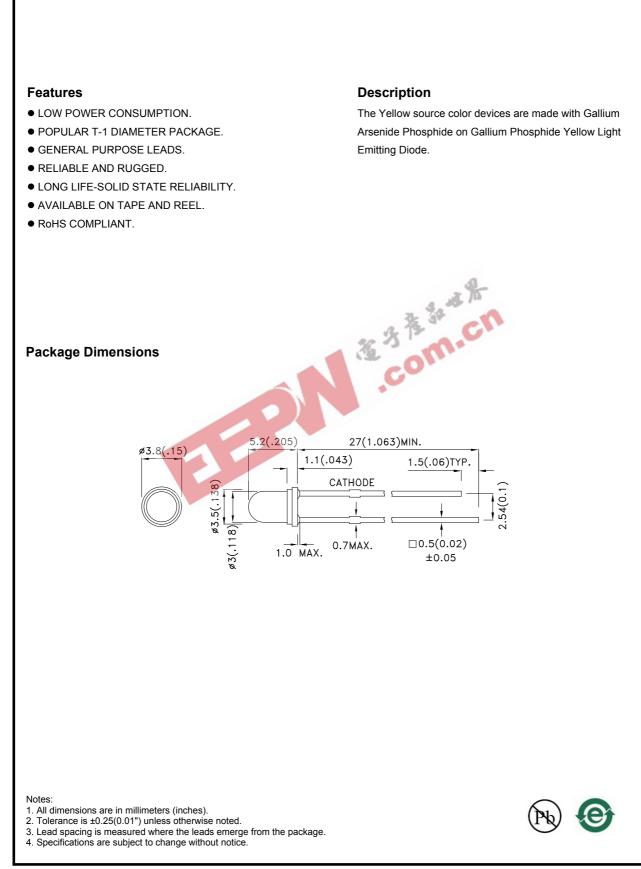
T-1 (3mm) SOLID STATE LAMP

Yellow

Part Number: WP132XYC



SPEC NO: DSAF2137 APPROVED: WYNEC DATE: MAY/10/2007 DRAWN: Y.L.LI PAGE: 1 OF 6 ERP: 1101001162

Selection Guide lv (mcd) [2] Viewing @ 10mA Angle [1] Part No. Dice Lens Type 201/2 Min. Тур. WP132XYC Yellow (GaAsP/GaP) WATER CLEAR 8 20 50°

Notes:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

2. Luminous intensity/ luminous Flux: +/-15%.

Electrical / Optical Characteristics at TA=25°C

Symbol	Parameter	Device	Тур.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Yellow	590	1. 15	nm	I⊧=20mA
λD [1]	Dominant Wavelength	Yellow	588	34	nm	I⊧=20mA
Δλ1/2	Spectral Line Half-width	Yellow	35	m.	nm	I⊧=20mA
С	Capacitance	Yellow	20		pF	VF=0V;f=1MHz
VF [2]	Forward Voltage	Yellow	2.1	2.5	V	I⊧=20mA
IR	Reverse Current	Yellow		10	uA	VR = 5V
Notes: 1.Wavelength 2. Forward Vo	: +/-1nm. Jitage: +/-0.1V.					

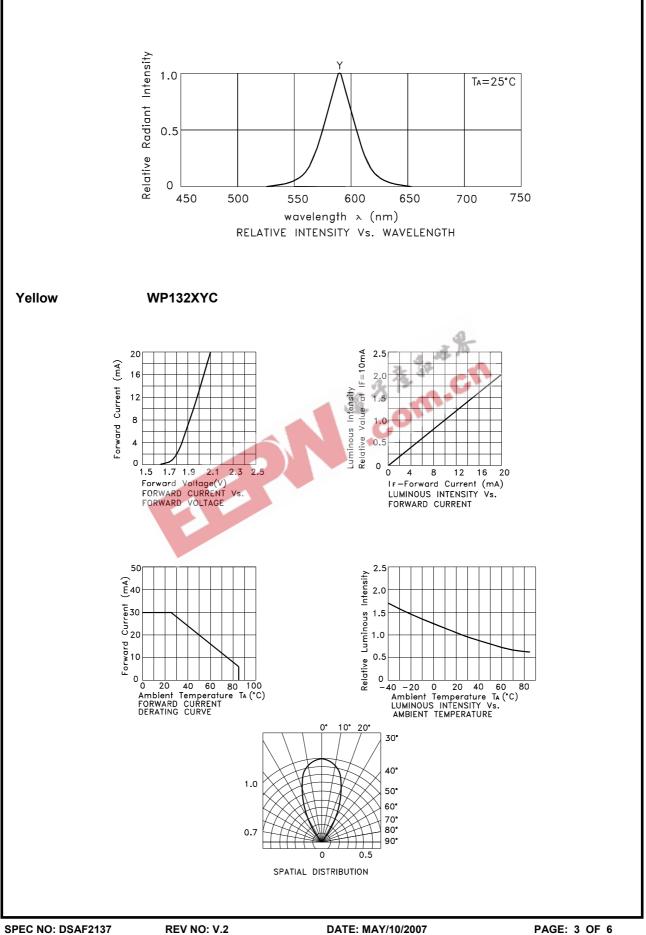
Absolute Maximum Ratings at TA=25°C

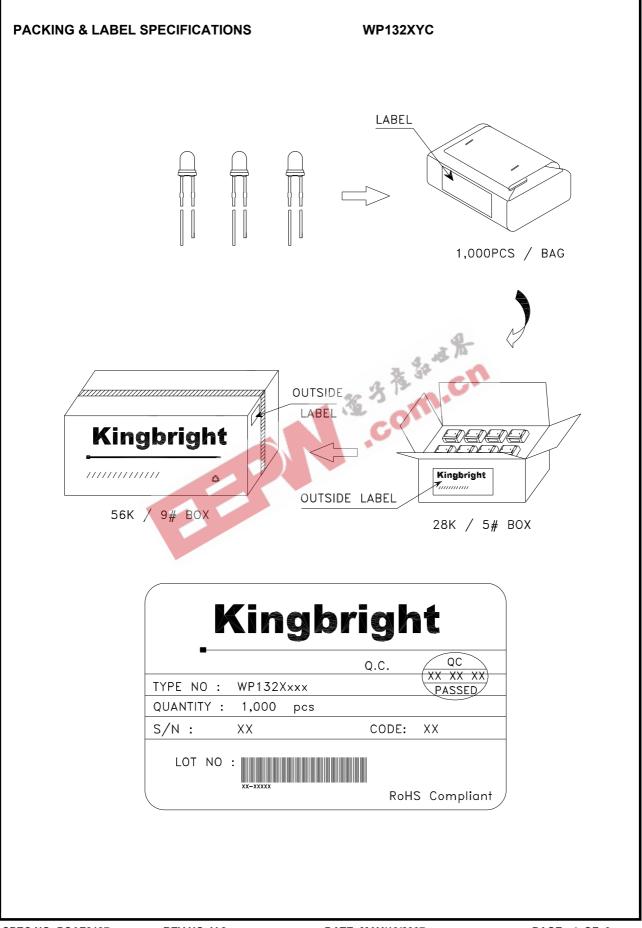
Parameter	Yellow	Units		
Power dissipation	75	mW		
DC Forward Current	30	mA		
Peak Forward Current [1]	140	mA		
Reverse Voltage	5	V		
Operating/Storage Temperature	-40°C To +85°C			
Lead Solder Temperature [2]	260°C For 3 Seconds			
Lead Solder Temperature [3]	260°C For 5 Seconds	260°C For 5 Seconds		
Lead Solder Temperature [3]	260°C For 5 Seconds			

Notes

1. 1/10 Duty Cycle, 0.1ms Pulse Width.

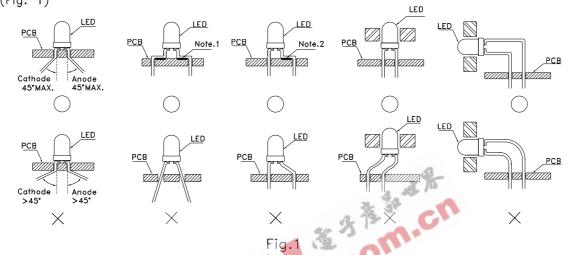
2. 2mm below package base.
3. 5mm below package base.





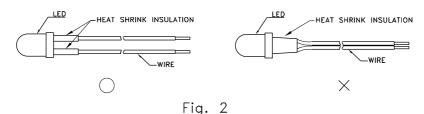
LED MOUNTING METHOD

 The lead pitch of the LED must match the pitch of the mounting holes on the PCB during component placement. Lead-forming may be required to insure the lead pitch matches the hole pitch. Refer to the figure below for proper lead forming procedures. (Fig. 1)

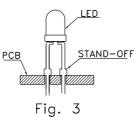


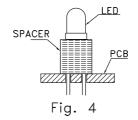
" \bigcirc " Correct mounting method " \times " Incorrect mounting method Note 1-2 : Do not route PCB trace in the contact area between the leadframe and the PCB to prevent short-circuits.

2. When soldering wire to the LED, use individual heat-shrink tubing to insulate the exposed leads to prevent accidental contact short-circuit. (Fig. 2)



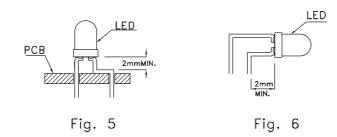
3. Use stand-offs (Fig. 3) or spacers (Fig. 4) to securely position the LED above the PCB.



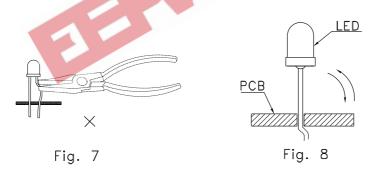


LEAD FORMING PROCEDURES

1. Maintain a minimum of 2mm clearance between the base of the LED lens and the first lead bend. (Fig. 5 and 6)



- 2. Lead forming or bending must be performed before soldering, never during or after Soldering.
- 3. Do not stress the LED lens during lead-forming in order to fractures in the lens epoxy and damage the internal structures.
- 4. During lead forming, use tools or jigs to hold the leads securely so that the bending force will not be transmitted to the LED lens and its internal structures. Do not perform lead forming once the component has been mounted onto the PCB. (Fig. 7)
- 5. Do not bend the leads more than twice. (Fig. 8)



6. After soldering or other high-temperature assembly, allow the LED to cool down to 50°C before applying outside force (Fig. 9). In general, avoid placing excess force on the LED to avoid damage. For any questions please consult with Kingbright representative for proper handling procedures.

